

BAT 49

SMALL SIGNAL SCHOTTKY DIODE

DO 41

(Glass)

DESCRIPTION

General purpose metal to silicon diode featuring very low turn-on voltage and fast switching. This device has integrated protection against excessive voltage such as electrostatic discharges.

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit	
V _{RRM}	Repetitive Peak Reverse Voltage		80	V
IF	Forward Continuous Current*	$T_a = 70 \ ^{\circ}C$	500	mA
I _{FRM}	Repetitive Peak Forward Current*	$\begin{array}{c} t_p = 1s \\ \delta \leq 0.5 \end{array}$	3	A
I _{FSM}	Surge non Repetitive Forward Current*	$t_p \le 10ms$	10	А
T _{stg} Tj	Storage and Junction Temperature Range		- 65 to 150 - 65 to 125	°C ℃
TL	Maximum Lead Temperature for Soldering during 10s at 4mm from Case		230	°C

THERMAL RESISTANCE

Symbol	Test Conditions	Value	Unit	
R _{th(j-a)}	Junction-ambient*	110	°C/W	

ELECTRICAL CHARACTERISTICS

STATIC CHARACTERISTICS

Symbol	Test Conditions	Min.	Тур.	Max.	Unit
I _R * *	$T_j = 25^{\circ}C$ $V_R = 80V$			200	μA
V _F * *	$T_j = 25^{\circ}C$ $I_F = 10mA$			0.32	V
	$T_j = 25^{\circ}C$ $I_F = 100mA$			0.42	
	$T_j = 25^{\circ}C$ $I_F = 1A$			1	

DYNAMIC CHARACTERISTICS

Symbol	Test Conditions			Min.	Тур.	Max.	Unit
С	T _j = 25°C	f = 1MHz	$V_R = 0V$		120		pF
			$V_R = 5V$		35		

* On infinite heatsink with 4mm lead length ** Pulse test: $t_p \leq 300 \mu s ~~\delta < 2 \mbox{\%}.$

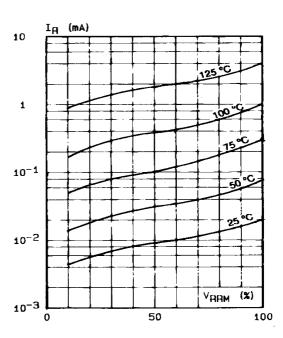
August 1999 Ed : 1A

(mA) I_{F} 103 10² 10 100 °C = j 1 25 °C = тj - -55 °C Tj 10⁻¹ ٧F (V) 10-2 0.2 0.4 0.6 0.8 o

Figure 1. Forward current versus forward voltage at low level (typical values).

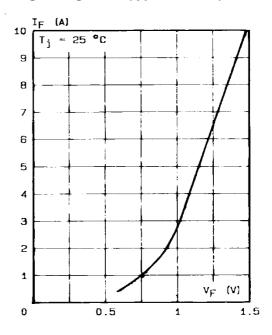
Figure 3. Reverse current versus junction temperature.

I_R (mA) 10² 90 % confidence 10 mах typ. 1 10^{-1} т_ј (°с) 10-2 0 50 100 150 Figure 4. Reverse current versus V_{RRM} in per cent.



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Figure 2. Forward current versus forward voltage at high level (typical values).



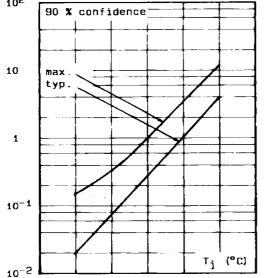




Figure 5. Capacitance C versus reverse applied voltage V_{R} (typical values).

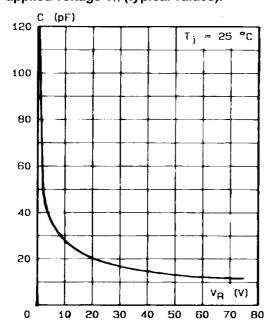


Figure 6. Surge non repetitive forward current for a rectangular pulse with $t \leq$ 10 ms.

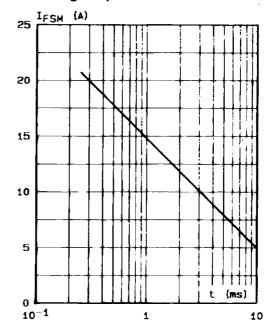
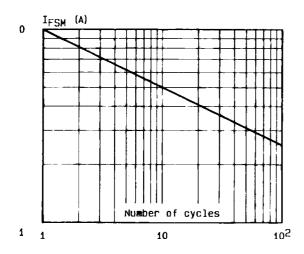
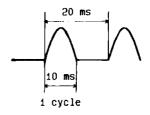


Figure 7. Surge non repetitive forward current versus number of cycles.

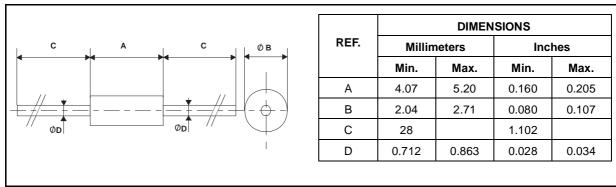




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PACKAGE MECHANICAL DATA

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Cooling method : by convection and conduction Marking: clear, ring at cathode end. Weight: 0.34g

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